ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

IPC-A-610D

Acceptability of Electronic Assemblies

IPC-A-610D

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- Include a feedback system on use and problems for future improvement

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Acceptability of Electronic Assemblies

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Foreword

If a conflict occurs between the English and translated versions of this document, the English version will take precedence.

1.1 Scope

This standard is a collection of visual quality acceptability requirements for electronic assemblies.

This document presents acceptance requirements for the manufacture of electrical and electronic assemblies. Historically, electronic assembly standards contained a more comprehensive tutorial addressing principles and techniques. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-HDBK-610, and IPC J-STD-001.

The criteria in this standard are not intended to define processes to accomplish assembly operations nor is it intended to authorize repair/modification or change of the customer's product. For instance, the presence of criteria for adhesive bonding of components does not imply/authorize/require the use of adhesive bonding, and the depiction of a lead wrapped clockwise around a terminal does not imply/authorize/require that all leads/wires be wrapped in the clockwise direction.

IPC-A-610 has criteria outside the scope of IPC J-STD-001 defining handling, mechanical and other workmanship requirements. Table 1-1 is a summary of related documents.

Table 1-1 Summary of Related Documents

Document Purpose	Spec.#	Definition
Design Standard	IPC-2220 (Series) IPC-SM-782 IPC-CM-770	Design requirements reflecting three levels of complexity (Levels A, B, and C) indicating finer geometries, greater densities, more process steps to produce the product. Component and Assembly Process Guidelines to assist in the design of the bare board and the assembly where the bare board processes concentrate on land patterns for surface mount and the assembly concentrates on surface mount and through-hole principles which are usually incorporated into the design process and the documentation.
End Item Documentation	IPC-D-325	Documentation depicting bare board specific end product requirements designed by the customer or end item assembly requirements. Details may or may not reference industry specifications or workmanship standards as well as customer's own preferences or internal standard requirements.
End Item Standards	IPC J-STD-001	Requirements for soldered electrical and electronic assemblies depicting minimum end product acceptable characteristics as well as methods for evaluation (test methods), frequency of testing and applicable ability of process control requirements.
Acceptability Standard	IPC-A-610	Pictorial interpretive document indicating various characteristics of the board and/or assembly as appropriate relating to desirable conditions that exceed the minimum acceptable characteristics indicated by the end item performance standard and reflect various out-of-control (process indicator or defect) conditions to assist the shop process evaluators in judging need for corrective action.
Training Programs (Optional)		Documented training requirements for teaching and learning process procedures and techniques for implementing acceptance requirements of either end item standards, acceptability standards, or requirements detailed on the customer documentation.
Rework and Repair	IPC-7711A/ IPC-7721A	Documentation providing the procedures to accomplish conformal coating and component removal and replacement, solder resist repair, and modification/repair of laminate material, conductors, and plated-through holes.